



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-12-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB80N4F6AG	T2D2*6D44AC2	A	SHENZHEN B/E	2015-12-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	T2D2*6D44AC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.902	mg	supplier	die	Silicon (Si)	7440-21-3		2.819	mg	971399	2043
				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	11371	24
				supplier	Passivation	Silicon Oxide	7631-86-9		0.015	mg	5169	11
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	689	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	8270	17
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.009	mg	3101	7
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	474
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	733
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	3.344	mg	954883	2423
Soft solder	Solder	3.502	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.344	mg	954883	2423
				supplier	solder	Silver (Ag)	7440-22-4		0.088	mg	25128	64
				supplier	solder	Tin (Sn)	7440-31-5		0.070	mg	19989	51
Bonding wires	Other inorganic materials	2.525	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.524	mg	999683	1829
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	317	1
				supplier	mold compound	Silica, vitreous	60676-86-0		474.746	mg	806000	344019
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		41.231	mg	70000	29878
				supplier	mold compound	Phenol resin	9003-35-4		23.561	mg	40001	17073
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		35.341	mg	60000	25609
Encapsulation	Other Organic Materials	589.015	mg	supplier	mold compound	Antimony Trioxide	1309-64-4		7.068	mg	12000	5122
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		4.123	mg	7000	2988
				supplier	mold compound	Carbon black	1333-86-4		2.945	mg	5000	2134
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804
				supplier	mold compound	Epoxy Resin	1309-64-4		7.068	mg	12000	5122
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		35.341	mg	60000	25609